



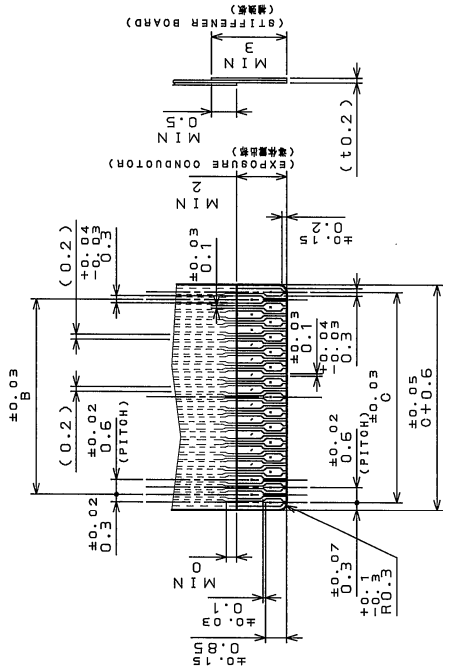
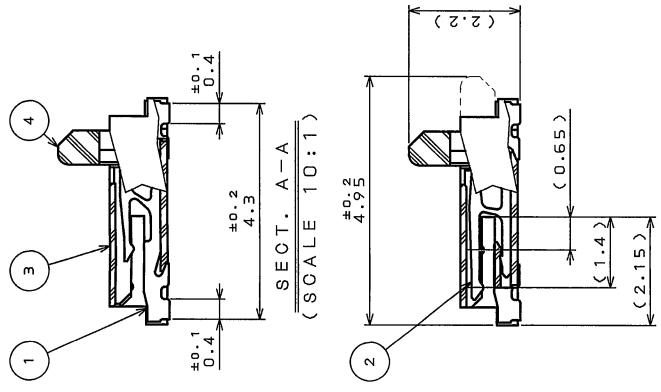
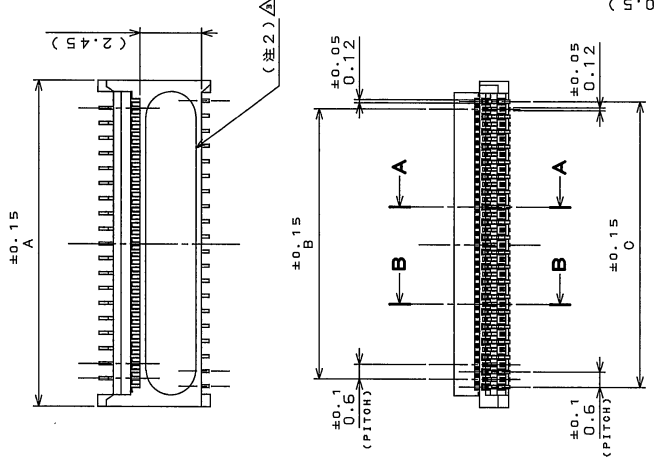
**THE DATASHEET OF  
FB8S029JA1R2000**



679901PS  
(-ON 9N1MVRG)各型図

REV.	DATE	DESCRIPTION	CHK.	APPD.
1	13.Feb.2007	ADDED AND DELETED ITEMS	N.IKENAGA	T.KUDOU
2	15.May.2007	ADDED LOT NUMBER	N.IKENAGA	T.KUDOU
3	3.Oct.2007	ADDED ITEMS	N.IKENAGA	T.KUDOU

REV.	DATE	DESCRIPTION	CHK.	APPD.
4	3.Oct.2007	ADDED ITEMS	N.IKENAGA	T.KUDOU



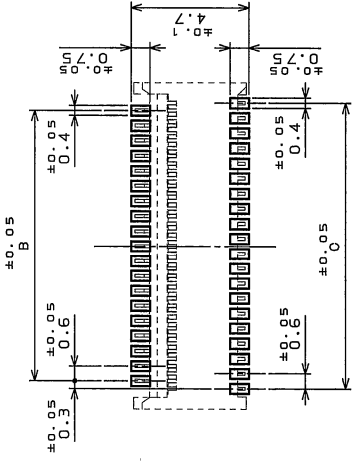
APPLICABLE F.P.C DIMENSION(REF.)  
適合FPC寸法(参考)  
( THICKNESS: 0.2±0.03 )

NOTE1.POLYIMIDE SHOULD BE USED AS A STIFFENER BOARD AND THERMOSETTING ADHESIVE SHOULD BE USED.  
BARE TRACES SHOULD BE GIVEN GOLD PLATING.  
NOTE2.LOT NUMBER IS MARKED ON THE TOP OF THE CONNECTOR.

MATED CONDITION(REF.)  
嵌合状態図(参考)

TABLE 1

NO. OF CONTACT	A	B	C
△ 17	6.4	4.2	4.8
△ 23	8.2	6.0	6.6
△ 25	8.8	6.6	7.2
△ 29	10.0	7.8	8.4
△ 31	10.6	8.4	9.0
△ 33	11.2	9.0	9.6
△ 35	11.8	9.6	10.2
△ 39	13.0	10.8	11.4
△ 41	13.6	11.4	12.0
△ 45	14.8	12.6	13.2
△ 51	16.6	14.4	15.0



APPLICABLE P.C.B. DIMENSION(REF.)  
適合基板寸法(参考)

NO.	DESCRIPTION	QTY.	REMARKS
4	ACTUATOR	1	GLASS FILLED NY
3	BASE INSULATOR	1	GLASS FILLED LOP
2	CONTACT 2	2	COPPER ALLOY
1	CONTACT 1	2	COPPER ALLOY
仕様書(SPECIFICATION) JAS-10358 仕様の詳細は「リミット」を使用し、接着剤は熱硬化性を使用すること。 X、仕上りは金メッキのこと。 △注2.ロット番号がコネクタ上部に表記されます。			
原簿(ORIGINAL DATE) 31.JULI.2006 製図(原簿) 31.JULI.2006 担当者 N.IKENAGA 承認者 T.KUDOU 検査者 K.IBARAKI			
種別(GENERAL TOLERANCE) 公差(DIMENSION) 角度(ANGLES) ・ ±0.8 X° ± ・ X ±0.4 X° ± ・ XX ±0.1 X° ± ・ XXX ±			
社名(TITLE) FB88***JA1 社名(SCALE) 列次(SERIES) FB8 社名(TITLE) JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. 社名(REFERENCE) 日本航空電子工業株式会社			
図面番号(DRAWING NO.) SJ106679 版数(VERSION) 4			

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